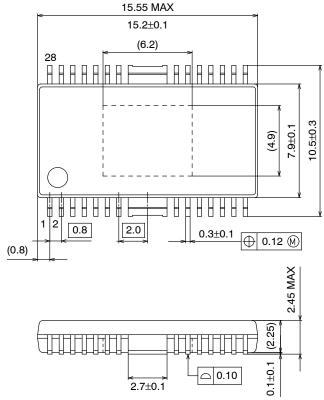
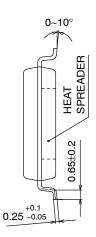


## **HSOP28H (375mil)** CASE 943AB ISSUE A

**DATE 08 NOV 2013** 



2.7±0.1



## **GENERIC** MARKING DIAGRAM\*



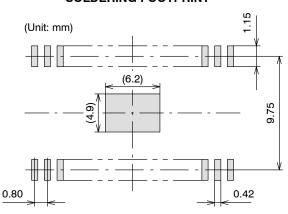
XXXXX = Specific Device Code Y = Year M = MonthDDD = Additional Traceability Data

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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DESCRIPTION:	HSOP28H (375 MIL)	PAGE 1 OF 3	

△ 0.10

## **SOLDERING FOOTPRINT\***



## NOTES:

- 1. The measurements are for reference only, and unable to guarantee.
- 2. Please take appropriate action to design the actual Exposed Die Pad and Fin portion.
- 3. After setting, verification on the product must be done.

  (Although there are no recommended design for Exposed Die Pad and Fin portion Metal mask and shape for Through–Hole pitch (Pitch & Via etc), checking the soldered joint condition and reliability verification of soldered joint will be needed. Void gradient insufficient thickness of soldered joint or bond degradation could lead IC destruction because thermal conduction to substrate becomes poor.)

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PAGE 3 OF 3

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0	RELEASED FOR PRODUCTION FROM SANYO ENACT# S-033 TO ON SEMICONDUCTOR. REQ. BY D. TRUHITTE.	30 NOV 2011		
A	ADDED MARKING AND SOLDER FOOTPRINT INFORMATION. REQ. BY D. TRUHITTE.	08 NOV 2013		

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